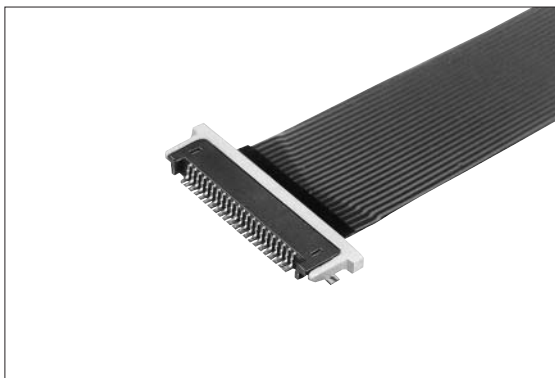


# FP-12 Series 0.5mm Pitch (SMT)



### Features

1. Low profile of 1.2mm height when mounted.
2. Our structure to hold the FPC temporary, provides easy operability.
3. With a mold attached to the bottom (board contact end).
4. Using the ZIF structure.
5. Either upper or lower contact available.
6. Supplied in the embossed taping with automatic mounter.

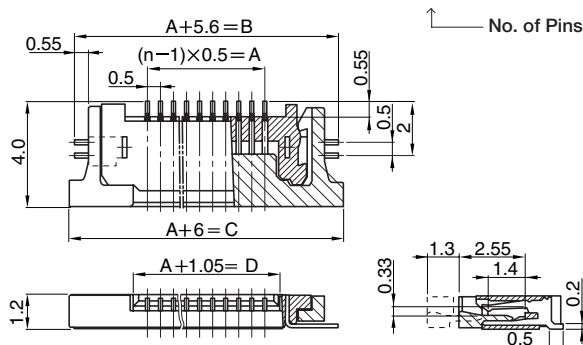
### Specification

1. Rating : 0.3A, 50V AC/DC
2. Contact Resistance : 30mΩ max., initially
3. Insulation Resistance : 100MΩ min. at 100V DC
4. Withstanding Voltage : 100V AC (for one minute)
5. Operating Temperature Range : -40°C to +85°C

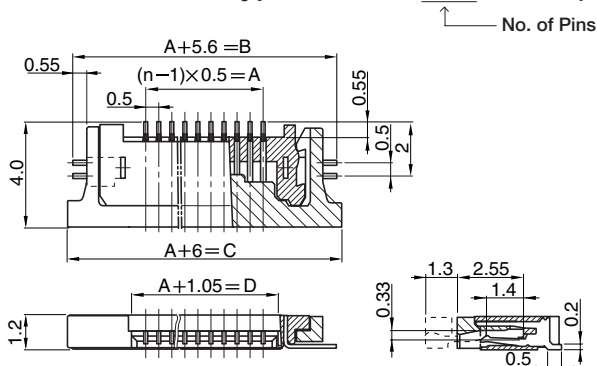
### Material and Plating

- Housing : Thermoplastic Resin, Black, 94V-0
- Cover : Thermoplastic Resin, Natural Color, 94V-0
- Contact : Cu Alloy, Au Plating
- Hold Down : Cu Alloy, Sn Plating

### ● Upper Contact Type CFP45□□-0150F(5~30P) CFP45□□-0250F(32,34,36P)

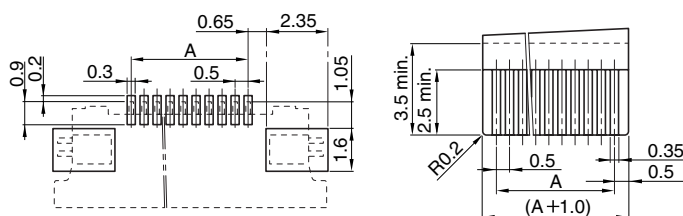


### ● Lower Contact Type CFP46□□-0150F(5~30P)



□□ No. of Pins	A	B	C	D	□□ No. of Pins	A	B	C	D
05	2.0	7.6	8.0	3.05	20	9.5	15.1	15.5	10.55
06	2.5	8.1	8.5	3.55	21	10.0	15.6	16.0	11.05
07	3.0	8.6	9.0	4.05	22	10.5	16.1	16.5	11.55
08	3.5	9.1	9.5	4.55	23	11.0	16.6	17.0	12.05
09	4.0	9.6	10.0	5.05	24	11.5	17.1	17.5	12.55
10	4.5	10.1	10.5	5.55	25	12.0	17.6	18.0	13.05
11	5.0	10.6	11.0	6.05	26	12.5	18.1	18.5	13.55
12	5.5	11.1	11.5	6.55	27	13.0	18.6	19.0	14.05
13	6.0	11.6	12.0	7.05	28	13.5	19.1	19.5	14.55
14	6.5	12.1	12.5	7.55	29	14.0	19.6	20.0	15.05
15	7.0	12.6	13.0	8.05	30	14.5	20.1	20.5	15.55
16	7.5	13.1	13.5	8.55	32	15.5	21.1	21.5	16.55
17	8.0	13.6	14.0	9.05	34	16.5	22.1	22.5	17.55
18	8.5	14.1	14.5	9.55	36	17.5	23.1	23.5	18.55
19	9.0	14.6	15.0	10.05					

### ■ P.C. Board Dimension ■ Applicable FPC Dimension (t=0.3±0.03)



- FPC plating to recommend : Au plating